Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	60MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	47
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc2132fbd64-01-11

3.1 Ordering options

Table 2. Ordering options

Type number	Flash memory	RAM	ADC	DAC	Enhanced UARTs, ADC, Fast I/Os, and BOD	Temperature range
LPC2131FBD64/01	32 kB	8 kB	1	-	yes	−40 °C to +85 °C
LPC2132FBD64/01	64 kB	16 kB	1	1	yes	−40 °C to +85 °C
LPC2132FHN64/01	64 kB	16 kB	1	1	yes	−40 °C to +85 °C
LPC2134FBD64/01	128 kB	16 kB	2	1	yes	−40 °C to +85 °C
LPC2136FBD64/01	256 kB	32 kB	2	1	yes	−40 °C to +85 °C
LPC2138FBD64/01	512 kB	32 kB	2	1	yes	−40 °C to +85 °C
LPC2138FHN64/01	512 kB	32 kB	2	1	yes	−40 °C to +85 °C

5. Pinning information

5.1 Pinning

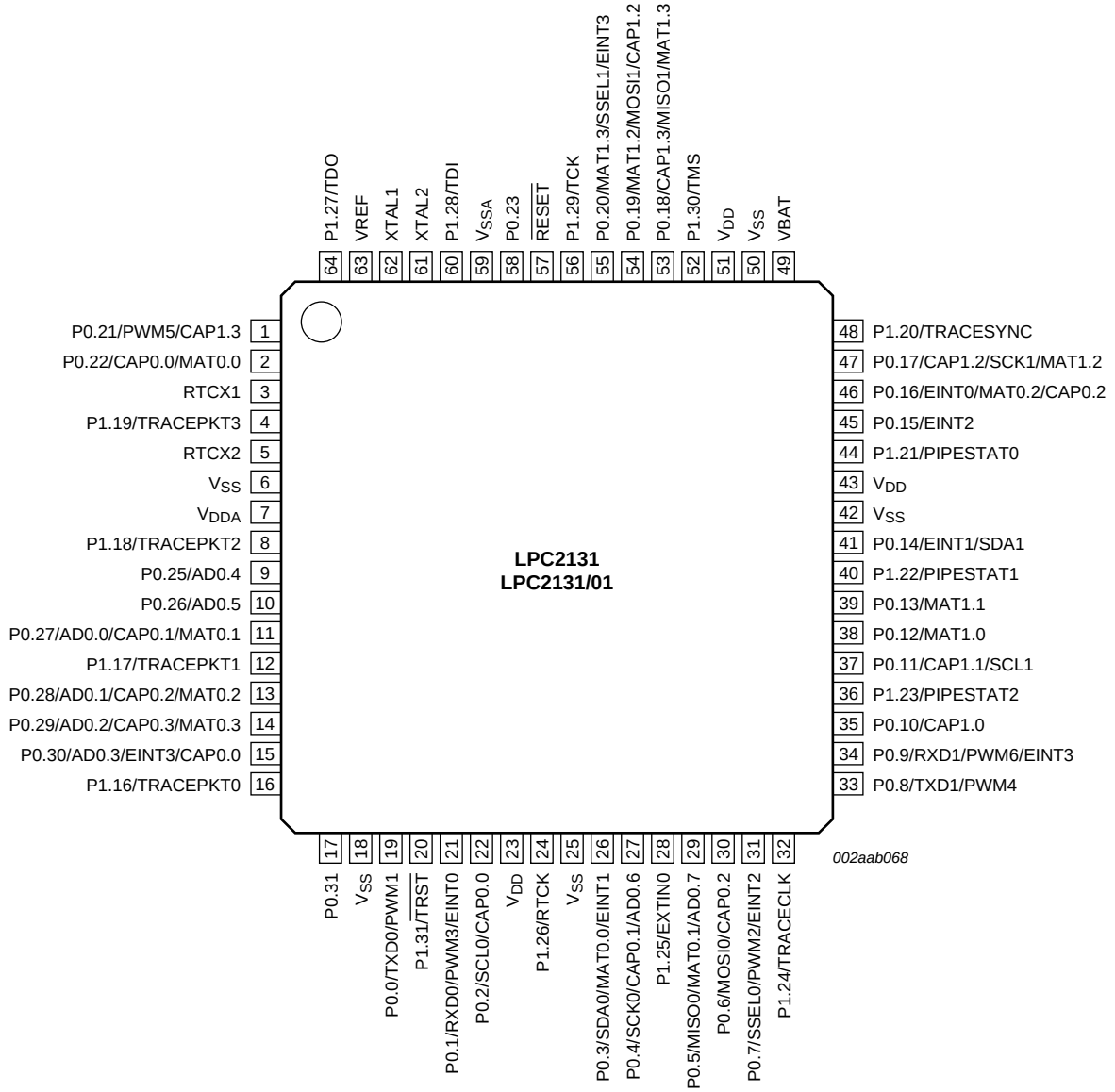


Fig 2. LPC2131 LQFP64 pin configuration

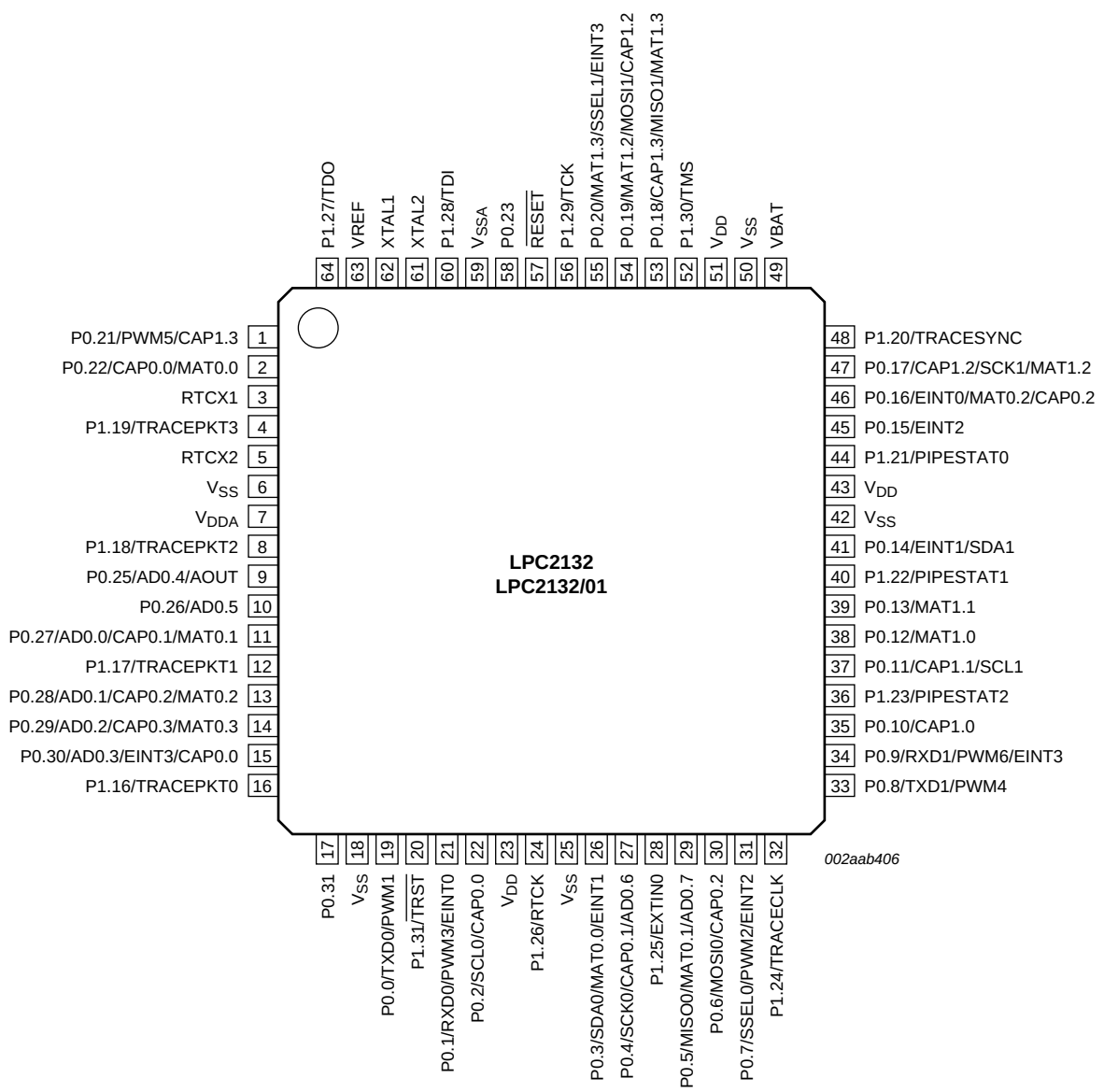


Fig 3. LPC2132 LQFP64 pin configuration

5.2 Pin description

Table 3. Pin description

Symbol	Pin	Type	Description
P0.0 to P0.31		I/O	**Port 0:** Port 0 is a 32-bit I/O port with individual direction controls for each bit. Total of 31 pins of the Port 0 can be used as a general purpose bidirectional digital I/Os while P0.31 is output only pin. The operation of port 0 pins depends upon the pin function selected via the pin connect block. Pin P0.24 is not available.
P0.0/TXD0/ PWM1	19[1]	O	**TXD0 —** Transmitter output for UART0.
		O	**PWM1 —** Pulse Width Modulator output 1.
P0.1/RXD0/ PWM3/EINT0	21[2]	I	**RXD0 —** Receiver input for UART0.
		O	**PWM3 —** Pulse Width Modulator output 3.
		I	**EINT0 —** External interrupt 0 input.
P0.2/SCL0/ CAP0.0	22[3]	I/O	**SCL0 —** I^2C0 clock input/output. Open drain output (for I^2C-bus compliance).
		I	**CAP0.0 —** Capture input for Timer 0, channel 0.
P0.3/SDA0/ MAT0.0/EINT1	26[3]	I/O	**SDA0 —** I^2C0 data input/output. Open drain output (for I^2C-bus compliance).
		O	**MAT0.0 —** Match output for Timer 0, channel 0.
		I	**EINT1 —** External interrupt 1 input.
P0.4/SCK0/ CAP0.1/AD0.6	27[4]	I/O	**SCK0 —** Serial clock for SPI0. SPI clock output from master or input to slave.
		I	**CAP0.1 —** Capture input for Timer 0, channel 1.
		I	**AD0.6 —** ADC 0, input 6. This analog input is always connected to its pin.
P0.5/MISO0/ MAT0.1/AD0.7	29[4]	I/O	**MISO0 —** Master In Slave V_{DD} = 3.6 V for SPI0. Data input to SPI master or data output from SPI slave.
		O	**MAT0.1 —** Match output for Timer 0, channel 1.
		I	**AD0.7 —** ADC 0, input 7. This analog input is always connected to its pin.
P0.6/MOSI0/ CAP0.2/AD1.0	30[4]	I/O	**MOSI0 —** Master Out Slave In for SPI0. Data output from SPI master or data input to SPI slave.
		I	**CAP0.2 —** Capture input for Timer 0, channel 2.
		I	**AD1.0 —** ADC 1, input 0. This analog input is always connected to its pin. Available in LPC2134/36/38 only.
P0.7/SSEL0/ PWM2/EINT2	31[2]	I	**SSEL0 —** Slave Select for SPI0. Selects the SPI interface as a slave.
		O	**PWM2 —** Pulse Width Modulator output 2.
		I	**EINT2 —** External interrupt 2 input.
P0.8/TXD1/ PWM4/AD1.1	33[4]	O	**TXD1 —** Transmitter output for UART1.
		O	**PWM4 —** Pulse Width Modulator output 4.
		I	**AD1.1 —** ADC 1, input 1. This analog input is always connected to its pin. Available in LPC2134/36/38 only.
P0.9/RXD1/ PWM6/EINT3	34[2]	I	**RXD1 —** Receiver input for UART1.
		O	**PWM6 —** Pulse Width Modulator output 6.
		I	**EINT3 —** External interrupt 3 input.
P0.10/RTS1/ CAP1.0/AD1.2	35[4]	O	**RTS1 —** Request to Send output for UART1. Available in LPC2134/36/38.
		I	**CAP1.0 —** Capture input for Timer 1, channel 0.
		I	**AD1.2 —** ADC 1, input 2. This analog input is always connected to its pin. Available in LPC2134/36/38 only.

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
P0.23	58[1]	I/O	General purpose digital input/output pin.
P0.25/AD0.4/ AOUT	9[5]	I	**AD0.4 —** ADC 0, input 4. This analog input is always connected to its pin.
		O	**AOUT —** DAC output. Not available in LPC2131.
P0.26/AD0.5	10[4]	I	**AD0.5 —** ADC 0, input 5. This analog input is always connected to its pin.
P0.27/AD0.0/ CAP0.1/MAT0.1	11[4]	I	**AD0.0 —** ADC 0, input 0. This analog input is always connected to its pin.
		I	**CAP0.1 —** Capture input for Timer 0, channel 1.
		O	**MAT0.1 —** Match output for Timer 0, channel 1.
P0.28/AD0.1/ CAP0.2/MAT0.2	13[4]	I	**AD0.1 —** ADC 0, input 1. This analog input is always connected to its pin.
		I	**CAP0.2 —** Capture input for Timer 0, channel 2.
		O	**MAT0.2 —** Match output for Timer 0, channel 2.
P0.29/AD0.2/ CAP0.3/MAT0.3	14[4]	I	**AD0.2 —** ADC 0, input 2. This analog input is always connected to its pin.
		I	**CAP0.3 —** Capture input for Timer 0, channel 3.
		O	**MAT0.3 —** Match output for Timer 0, channel 3.
P0.30/AD0.3/ EINT3/CAP0.0	15[4]	I	**AD0.3 —** ADC 0, input 3. This analog input is always connected to its pin.
		I	**EINT3 —** External interrupt 3 input.
		I	**CAP0.0 —** Capture input for Timer 0, channel 0.
P0.31	17[6]	O	General purpose digital output only pin. **Important:** This pin MUST NOT be externally pulled LOW when $\overline{\text{RESET}}$ pin is LOW or the JTAG port will be disabled.
P1.0 to P1.31		I/O	**Port 1:** Port 1 is a 32-bit bidirectional I/O port with individual direction controls for each bit. The operation of port 1 pins depends upon the pin function selected via the pin connect block. Pins 0 through 15 of port 1 are not available.
P1.16/ TRACEPKT0	16[6]	O	**TRACEPKT0 —** Trace Packet, bit 0. Standard I/O port with internal pull-up.
P1.17/ TRACEPKT1	12[6]	O	**TRACEPKT1 —** Trace Packet, bit 1. Standard I/O port with internal pull-up.
P1.18/ TRACEPKT2	8[6]	O	**TRACEPKT2 —** Trace Packet, bit 2. Standard I/O port with internal pull-up.
P1.19/ TRACEPKT3	4[6]	O	**TRACEPKT3 —** Trace Packet, bit 3. Standard I/O port with internal pull-up.
P1.20/ TRACESYNC	48[6]	O	**TRACESYNC —** Trace Synchronization. Standard I/O port with internal pull-up. LOW on TRACESYNC while $\overline{\text{RESET}}$ is LOW enables pins P1.25:16 to operate as Trace port after reset.
P1.21/ PIPESTAT0	44[6]	O	**PIPESTAT0 —** Pipeline Status, bit 0. Standard I/O port with internal pull-up.
P1.22/ PIPESTAT1	40[6]	O	**PIPESTAT1 —** Pipeline Status, bit 1. Standard I/O port with internal pull-up.
P1.23/ PIPESTAT2	36[6]	O	**PIPESTAT2 —** Pipeline Status, bit 2. Standard I/O port with internal pull-up.
P1.24/ TRACECLK	32[6]	O	**TRACECLK —** Trace Clock. Standard I/O port with internal pull-up.
P1.25/EXTIN0	28[6]	I	**EXTIN0 —** External Trigger Input. Standard I/O with internal pull-up.

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
P1.26/RTCK	24[6]	I/O	**RTCK —** Returned Test Clock output. Extra signal added to the JTAG port. Assists debugger synchronization when processor frequency varies. Bidirectional pin with internal pull-up. LOW on RTCK while $\overline{\text{RESET}}$ is LOW enables pins P1.31:26 to operate as Debug port after reset.
P1.27/TDO	64[6]	O	**TDO —** Test Data out for JTAG interface.
P1.28/TDI	60[6]	I	**TDI —** Test Data in for JTAG interface.
P1.29/TCK	56[6]	I	**TCK —** Test Clock for JTAG interface.
P1.30/TMS	52[6]	I	**TMS —** Test Mode Select for JTAG interface.
P1.31/$\overline{\text{TRST}}$	20[6]	I	**$\overline{\text{TRST}}$ —** Test Reset for JTAG interface.
$\overline{\text{RESET}}$	57[7]	I	**External reset input:** A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. TTL with hysteresis, 5 V tolerant.
XTAL1	62[8]	I	Input to the oscillator circuit and internal clock generator circuits.
XTAL2	61[8]	O	Output from the oscillator amplifier.
RTCX1	3[9]	I	Input to the RTC oscillator circuit.
RTCX2	5[9]	O	Output from the RTC oscillator circuit.
V_{SS}	6, 18, 25, 42, 50	I	**Ground:** 0 V reference.
V_{SSA}	59	I	**Analog ground:** 0 V reference. This should nominally be the same voltage as V_{SS}, but should be isolated to minimize noise and error.
V_{DD}	23, 43, 51	I	**3.3 V power supply:** This is the power supply voltage for the core and I/O ports.
V_{DDA}	7	I	**Analog 3.3 V power supply:** This should be nominally the same voltage as V_{DD} but should be isolated to minimize noise and error. This voltage is used to power the on-chip PLL.
VREF	63	I	**ADC reference:** This should be nominally the same voltage as V_{DD} but should be isolated to minimize noise and error. Level on this pin is used as a reference for A/D and D/A convertor(s).
VBAT	49	I	**RTC power supply:** 3.3 V on this pin supplies the power to the RTC.

[1] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control.

[2] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns.

[3] Open drain 5 V tolerant digital I/O I^2C-bus 400 kHz specification compatible pad. It requires external pull-up to provide an output functionality.

[4] 5 V tolerant pad providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog input function. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns. When configured as an ADC input, digital section of the pad is disabled.

[5] 5 V tolerant pad providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog output function. When configured as the DAC output, digital section of the pad is disabled.

[6] 5 V tolerant pad with built-in pull-up resistor providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. The pull-up resistor's value ranges from 60 kΩ to 300 kΩ.

[7] 5 V tolerant pad providing digital input (with TTL levels and hysteresis) function only.

[8] Pad provides special analog functionality.

[9] When unused, the RTCX1 pin can be grounded or left floating. For lowest power leave it floating.
The other RTC pin, RTCX2, should be left floating.

6.5 Interrupt controller

The Vectored Interrupt Controller (VIC) accepts all of the interrupt request inputs and categorizes them as Fast Interrupt reQuest (FIQ), vectored Interrupt ReQuest (IRQ), and non-vectored IRQ as defined by programmable settings. The programmable assignment scheme means that priorities of interrupts from the various peripherals can be dynamically assigned and adjusted.

FIQ has the highest priority. If more than one request is assigned to FIQ, the VIC combines the requests to produce the FIQ signal to the ARM processor. The fastest possible FIQ latency is achieved when only one request is classified as FIQ, because then the FIQ service routine can simply start dealing with that device. But if more than one request is assigned to the FIQ class, the FIQ service routine can read a word from the VIC that identifies which FIQ source(s) is (are) requesting an interrupt.

Vectored IRQs have the middle priority. Sixteen of the interrupt requests can be assigned to this category. Any of the interrupt requests can be assigned to any of the 16 vectored IRQ slots, among which slot 0 has the highest priority and slot 15 has the lowest.

Non-vectored IRQs have the lowest priority.

The VIC combines the requests from all the vectored and non-vectored IRQs to produce the IRQ signal to the ARM processor. The IRQ service routine can start by reading a register from the VIC and jumping there. If any of the vectored IRQs are requesting, the VIC provides the address of the highest-priority requesting IRQs service routine, otherwise it provides the address of a default routine that is shared by all the non-vectored IRQs. The default routine can read another VIC register to see what IRQs are active.

6.5.1 Interrupt sources

Table 4 lists the interrupt sources for each peripheral function. Each peripheral device has one interrupt line connected to the Vectored Interrupt Controller, but may have several internal interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

Table 4. Interrupt sources

Block	Flag(s)	VIC channel #
WDT	Watchdog Interrupt (WDINT)	0
-	Reserved for software interrupts only	1
ARM Core	EmbeddedICE, DbgCommRX	2
ARM Core	EmbeddedICE, DbgCommTX	3
TIMER0	Match 0 to 3 (MR0, MR1, MR2, MR3) Capture 0 to 3 (CR0, CR1, CR2, CR3)	4
TIMER1	Match 0 to 3 (MR0, MR1, MR2, MR3) Capture 0 to 3 (CR0, CR1, CR2, CR3)	5
UART0	RX Line Status (RLS) Transmit Holding Register empty (THRE) RX Data Available (RDA) Character Time-out Indicator (CTI)	6

- Built-in baud rate generator.
- Standard modem interface signals included on UART1. (LPC2134/36/38 only)
- The LPC2131/32/34/36/38 transmission FIFO control enables implementation of software (XON/XOFF) flow control on both UARTs and hardware (CTS/RTS) flow control on the LPC2134/36/38 UART1 only.

6.10.2 UART features available in LPC213x/01 only

- Fractional baud rate generator enables standard baud rates such as 115200 to be achieved with any crystal frequency above 2 MHz.
- Auto-bauding.
- Auto-CTS/RTS flow-control fully implemented in hardware (LPC2134/36/38 only).

6.11 I^2C-bus serial I/O controller

The LPC2131/32/34/36/38 each contain two I^2C-bus controllers.

The I^2C-bus is bidirectional, for inter-IC control using only two wires: a Serial Clock Line (SCL), and a Serial DAta line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver or a transmitter with the capability to both receive and send information (such as memory)). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I^2C-bus is a multi-master bus, it can be controlled by more than one bus master connected to it.

This I^2C-bus implementation supports bit rates up to 400 kbit/s (Fast I^2C).

6.11.1 Features

- Standard I^2C compliant bus interface.
- Easy to configure as Master, Slave, or Master/Slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus may be used for test and diagnostic purposes.

6.12 SPI serial I/O controller

The LPC2131/32/34/36/38 each contain one SPI controller. The SPI is a full duplex serial interface, designed to be able to handle multiple masters and slaves connected to a given bus. Only a single master and a single slave can communicate on the interface during a given data transfer. During a data transfer the master always sends a byte of data to the slave, and the slave always sends a byte of data to the master.

6.12.1 Features

- Compliant with Serial Peripheral Interface (SPI) specification.
- Synchronous, Serial, Full Duplex, Communication.
- Combined SPI master and slave.
- Maximum data bit rate of one eighth of the input clock rate.

6.13 SSP serial I/O controller

The LPC2131/32/34/36/38 each contain one Serial Synchronous Port controller (SSP). The SSP controller is capable of operation on a SPI, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. However, only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. Often only one of these data flows carries meaningful data.

6.13.1 Features

- Compatible with Motorola SPI, 4-wire TI SSI and National Semiconductor Microwire buses.
- Synchronous Serial Communication.
- Master or slave operation.
- 8-frame FIFOs for both transmit and receive.
- Four bits to 16 bits per frame.

6.14 General purpose timers/external event counters

The Timer/Counter is designed to count cycles of the peripheral clock (PCLK) or an externally supplied clock, and optionally generate interrupts or perform other actions at specified timer values, based on four match registers. It also includes four capture inputs to trap the timer value when an input signal transitions, optionally generating an interrupt. Multiple pins can be selected to perform a single capture or match function, providing an application with ‘or’ and ‘and’, as well as ‘broadcast’ functions among them.

At any given time only one of peripheral’s capture inputs can be selected as an external event signal source, i.e., timer’s clock. The rate of external events that can be successfully counted is limited to PCLK/2. In this configuration, unused capture lines can be selected as regular timer capture inputs.

6.14.1 Features

- A 32-bit Timer/Counter with a programmable 32-bit Prescaler.
- External Event Counter or timer operation.
- Four 32-bit capture channels per timer/counter that can take a snapshot of the timer value when an input signal transitions. A capture event may also optionally generate an interrupt.
- Four 32-bit match registers that allow:
  - Continuous operation with optional interrupt generation on match.

- Match register updates are synchronized with pulse outputs to prevent generation of erroneous pulses. Software must ‘release’ new match values before they can become effective.
- May be used as a standard timer if the PWM mode is not enabled.
- A 32-bit Timer/Counter with a programmable 32-bit Prescaler.

6.18 System control

6.18.1 Crystal oscillator

On-chip integrated oscillator operates with external crystal in range of 1 MHz to 30 MHz and with external oscillator up to 50 MHz. The oscillator output frequency is called f_{osc} and the ARM processor clock frequency is referred to as CCLK for purposes of rate equations, etc. f_{osc} and CCLK are the same value unless the PLL is running and connected. Refer to Section 6.18.2 “PLL” for additional information.

6.18.2 PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up into the range of 10 MHz to 60 MHz with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32 (in practice, the multiplier value cannot be higher than 6 on this family of microcontrollers due to the upper frequency limit of the CPU). The CCO operates in the range of 156 MHz to 320 MHz, so there is an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider may be set to divide by 2, 4, 8, or 16 to produce the output clock. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset and may be enabled by software. The program must configure and activate the PLL, wait for the PLL to Lock, then connect to the PLL as a clock source. The PLL settling time is 100 μs.

6.18.3 Reset and wake-up timer

Reset has two sources on the LPC2131/32/34/36/38: the $\overline{\text{RESET}}$ pin and watchdog reset. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin with an additional glitch filter. Assertion of chip reset by any source starts the wake-up timer (see wake-up timer description below), causing the internal chip reset to remain asserted until the external reset is de-asserted, the oscillator is running, a fixed number of clocks have passed, and the on-chip flash controller has completed its initialization.

When the internal reset is removed, the processor begins executing at address 0, which is the reset vector. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

The wake-up timer ensures that the oscillator and other analog functions required for chip operation are fully functional before the processor is allowed to execute instructions. This is important at power on, all types of reset, and whenever any of the aforementioned functions are turned off for any reason. Since the oscillator and other functions are turned off during Power-down mode, any wake-up of the processor from Power-down mode makes use of the wake-up timer.

The wake-up timer monitors the crystal oscillator as the means of checking whether it is safe to begin code execution. When power is applied to the chip, or some event caused the chip to exit Power-down mode, some time is required for the oscillator to produce a signal of sufficient amplitude to drive the clock logic. The amount of time depends on many factors, including the rate of V_{DD} ramp (in the case of power on), the type of crystal and its electrical characteristics (if a quartz crystal is used), as well as any other external circuitry (e.g. capacitors), and the characteristics of the oscillator itself under the existing ambient conditions.

6.18.4 Brownout detector

The LPC2131/32/34/36/38 include 2-stage monitoring of the voltage on the V_{DD} pins. If this voltage falls below 2.9 V, the BOD asserts an interrupt signal to the Vectored Interrupt Controller. This signal can be enabled for interrupt; if not, software can monitor the signal by reading dedicated register.

The second stage of low-voltage detection asserts reset to inactivate the LPC2131/32/34/36/38 when the voltage on the V_{DD} pins falls below 2.6 V. This reset prevents alteration of the flash as operation of the various elements of the chip would otherwise become unreliable due to low voltage. The BOD circuit maintains this reset down below 1 V, at which point the POR circuitry maintains the overall reset.

Both the 2.9 V and 2.6 V thresholds include some hysteresis. In normal operation, this hysteresis allows the 2.9 V detection to reliably interrupt, or a regularly-executed event loop to sense the condition.

Features available only in LPC213x/01 parts include ability to put the BOD in power-down mode, turn it on or off and to control when the BOD will reset the LPC213x/01 microcontroller. This can be used to further reduce power consumption when a low power mode (such as Power Down) is invoked.

6.18.5 Code security

This feature of the LPC2131/32/34/36/38 allow an application to control whether it can be debugged or protected from observation.

If after reset on-chip bootloader detects a valid checksum in flash and reads 0x8765 4321 from address 0x1FC in flash, debugging will be disabled and thus the code in flash will be protected from observation. Once debugging is disabled, it can be enabled only by performing a full chip erase using the ISP.

6.18.6 External interrupt inputs

The LPC2131/32/34/36/38 include up to nine edge or level sensitive External Interrupt Inputs as selectable pin functions. When the pins are combined, external events can be processed as four independent interrupt signals. The External Interrupt Inputs can optionally be used to wake up the processor from Power-down mode.

6.18.7 Memory Mapping Control

The Memory Mapping Control alters the mapping of the interrupt vectors that appear beginning at address 0x0000 0000. Vectors may be mapped to the bottom of the on-chip flash memory, or to the on-chip static RAM. This allows code running in different memory spaces to have control of the interrupts.

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage (core and external rail)			–0.5	+3.6	V
V_{DDA}	analog 3.3 V pad supply voltage			–0.5	+4.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT	for the RTC		–0.5	+4.6	V
$V_{i(VREF)}$	input voltage on pin VREF			–0.5	+4.6	V
V_{IA}	analog input voltage	on ADC related pins		–0.5	+5.1	V
V_I	input voltage	5 V tolerant I/O pins; only valid when the V_{DD} supply voltage is present	[2]	–0.5	+6.0	V
		other I/O pins	[2][3]	–0.5	V_{DD} + 0.5	V
I_{DD}	supply current	per supply pin	[4]	-	100	mA
I_{SS}	ground current	per ground pin	[4]	-	100	mA
I_{sink}	sink current	for I^2C-bus; DC; T = 85 °C		-	20	mA
T_{stg}	storage temperature		[5]	–40	+125	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{ESD}	electrostatic discharge voltage	human body model	[6]			
		all pins		–4000	+4000	V

[1] The following applies to the Limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] Not to exceed 4.6 V.

[4] The peak current is limited to 25 times the corresponding maximum current.

[5] Dependent on package type.

[6] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

11. DAC electrical characteristics

Table 9. DAC electrical characteristics

V_{DDA} = 3.0 V to 3.6 V; T_{amb} = –40 °C to +85 °C unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
E_D	differential linearity error		-	±1	-	LSB
$E_{L(adj)}$	integral non-linearity		-	±1.5	-	LSB
E_O	offset error		-	0.6	-	%
E_G	gain error		-	0.6	-	%
C_L	load capacitance		-	200	-	pF
R_L	load resistance		1	-	-	kΩ

12. Application information

12.1 Crystal oscillator XTAL input and component selection

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i / (C_i + C_g)$. In slave mode, a minimum of 200 mV (RMS) is needed.

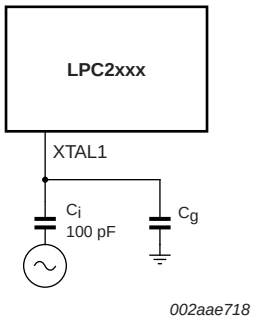


Fig 13. Slave mode operation of the on-chip oscillator

In slave mode the input clock signal should be coupled by means of a capacitor of 100 pF (Figure 13), with an amplitude between 200 mV (RMS) and 1000 mV (RMS). This corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTAL2 pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in Figure 14 and in Table 10 and Table 11. Since the feedback resistance is integrated on chip, only a crystal and the capacitances C_{X1} and C_{X2} need to be connected externally in case of fundamental mode oscillation (the fundamental frequency is represented by L, C_L and R_S). Capacitance C_P in Figure 14 represents the parallel package capacitance and should not be larger than 7 pF. Parameters F_{OSC}, C_L, R_S and C_P are supplied by the crystal manufacturer.

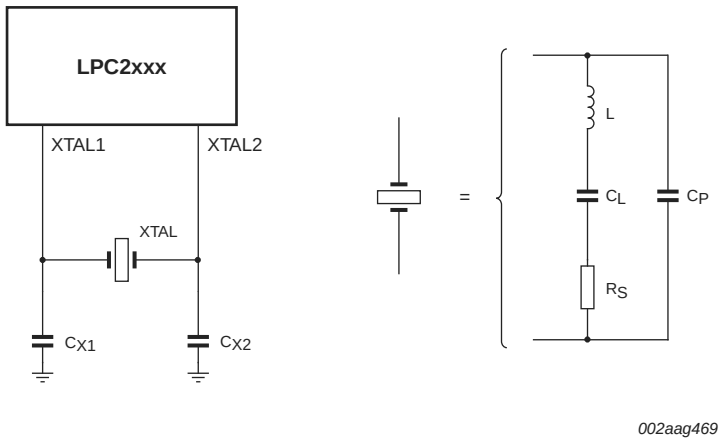


Fig 14. Oscillator modes and models: oscillation mode of operation and external crystal model used for C_{X1}/C_{X2} evaluation

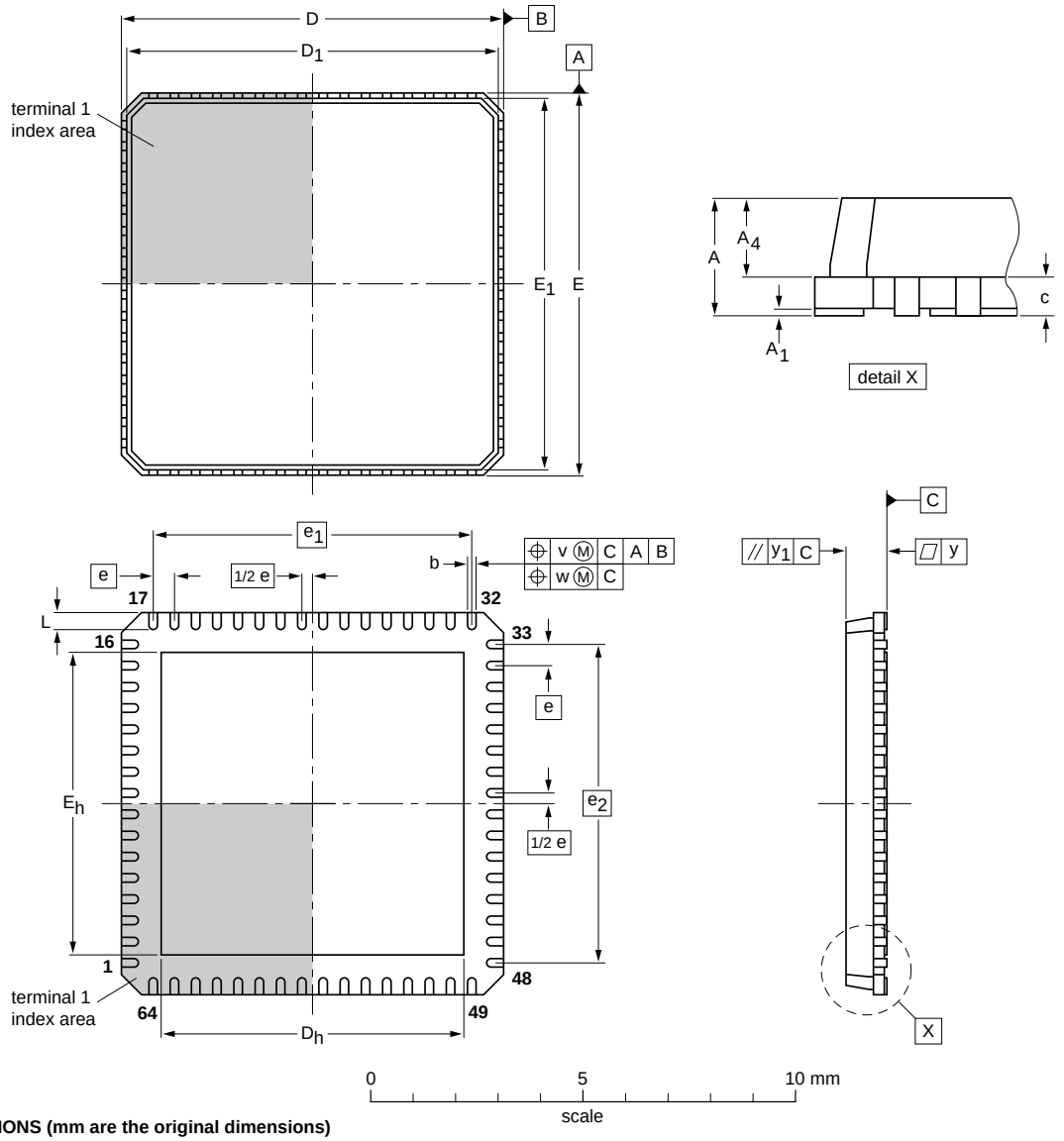
Table 10. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters): low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}/C_{X2}
1 MHz to 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF
5 MHz to 10 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 200 Ω	39 pF, 39 pF
	30 pF	< 100 Ω	57 pF, 57 pF
10 MHz to 15 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 60 Ω	39 pF, 39 pF
15 MHz to 20 MHz	10 pF	< 80 Ω	18 pF, 18 pF

Table 11. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters): high frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
15 MHz to 20 MHz	10 pF	< 180 Ω	18 pF, 18 pF
	20 pF	< 100 Ω	39 pF, 39 pF
20 MHz to 25 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 80 Ω	39 pF, 39 pF

HVQFN64: plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm **SOT804-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_4	b	c	D	D_1	D_h	E	E_1	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	1	0.05 0.00	0.80 0.65	0.30 0.18	0.2	9.05 8.95	8.95 8.55	7.25 6.95	9.05 8.95	8.95 8.55	7.25 6.95	0.5	7.5	7.5	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT804-2	- - -	MO-220	- - -			04-03-25

Fig 17. Package outline SOT804-2 (HVQFN64)

14. Abbreviations

Table 13. Acronym list

Acronym	Description
A/D	Analog-to-Digital
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
AMBA	Advanced Microcontroller Bus Architecture
APB	Advanced Peripheral Bus
BOD	BrownOut Detection
CPU	Central Processing Unit
DAC	Digital-to-Analog Converter
DCC	Debug Communications Channel
ETM	Embedded Trace Macrocell
FIFO	First In, First Out
GPIO	General Purpose Input/Output
JTAG	Joint Test Action Group
LSB	Least Significant Bit
PLL	Phase-Locked Loop
POR	Power-On Reset
PWM	Pulse Width Modulator
RAM	Random Access Memory
SPI	Serial Peripheral Interface
SRAM	Static Random Access Memory
SSP	Synchronous Serial Port
UART	Universal Asynchronous Receiver/Transmitter

15. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC2131_32_34_36_38 v.5.1	20110729	Product data sheet	-	LPC2131_32_34_36_38 v.5
Modifications:	• Parameter I_{sink} added in Table 5 “Limiting values”. • Table 6 “Static characteristics”: Updated crystal oscillator specs			
LPC2131_32_34_36_38 v.5	20110202	Product data sheet	-	LPC2131_32_34_36_38 v.4
Modifications:	• Table 3 “Pin description”: Added Table note [9] to RTCX1 and RTCX2 pins. • Table 6 “Static characteristics”, I^2C-bus pins: Changed typical hysteresis voltage from $0.5V_{DD}$ to $0.05V_{DD}$. • Table 6 “Static characteristics”: Removed table note for V_{IH} and V_{IL}. • Changed all occurrences of VPB to APB. • Table 6 “Static characteristics”: Added Table note [6] to V_I. • Table 6 “Static characteristics”, Standard port pins, $\overline{\text{RESET}}$, RTCK: V_{hys} hysteresis voltage (0.4 V) moved from typical to minimum. • Table 6 “Static characteristics”: Changed $V_{i(VREF)}$ minimum voltage from 3.0 V to 2.5 V. • Table 6 “Static characteristics”: Updated min, typical and max values for oscillator pins $V_{i(XTAL1)}$, $V_{o(XTAL2)}$, $V_{i(RTCX1)}$, and $V_{o(RTCX2)}$. • Added Section 11 “DAC electrical characteristics”. • Added Section 12 “Application information”.			
LPC2131_32_34_36_38 v.4	20071016	Product data sheet	-	LPC2131_32_34_36_38 v.3
LPC2131_32_34_36_38 v.3	20060921	Product data sheet	-	LPC2131_32_34_36_38 v.2
LPC2131_32_34_36_38 v.2	20050318	Preliminary data sheet	-	LPC2131_2132_2138 v.1
LPC2131_2132_2138 v.1	20041118	Preliminary data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

16.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

16.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

I^2C-bus — logo is a trademark of NXP B.V.

17. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**